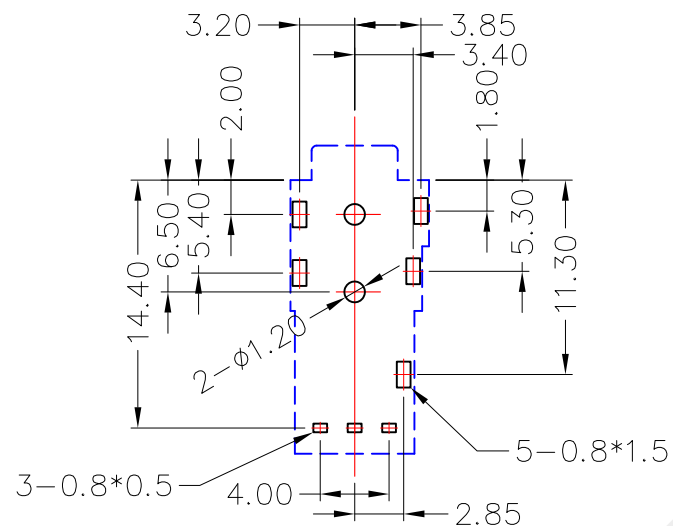
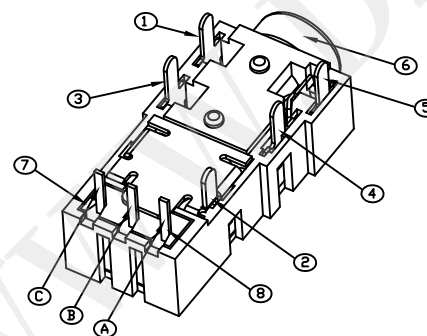
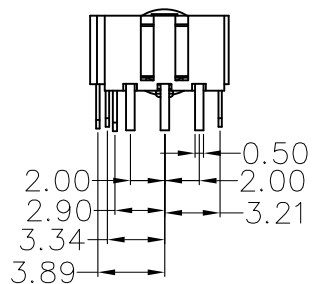
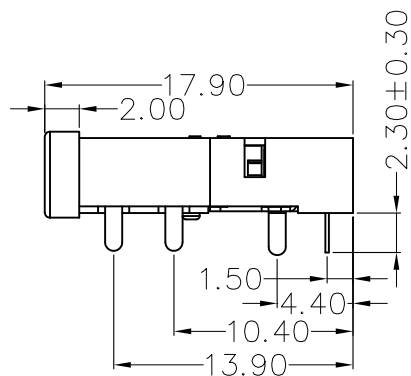
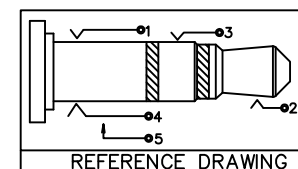
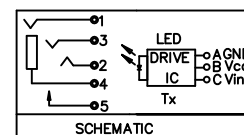


基板参考图(公差±0.3)
PCB LAYOUT(Tol.±0.3)



⑧	DRIVE IC(TX)			1	
⑦	COVER	HIGH-TEMP PLASTIC	BLACK	1	
⑥	HOUSING	HIGH-TEMP PLASTIC	BLACK	1	
⑤	DETECTOR	PHOSPHOR BRONZE	Au	1	Au 1u" & Ni 50u" min
④	GND	PHOSPHOR BRONZE	Au	1	
③	RIGHT CHANNEL	PHOSPHOR BRONZE	Au	1	
②	LEFT CHANNEL	PHOSPHOR BRONZE	Au	1	
①	DETECTOR	PHOSPHOR BRONZE	Au	1	
ITEM	DESCRIPTIONs	MATERIAL	FINISH	Q'TY	NOTE



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 光纤+耳机 (发射)	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. MOLD NO.	HYC-DLT13M1
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2014-02-23	DRAW NO:	HYC-1801243311
			SHEET NO.	1 OF 1